

L Number	Hits	Search Text	DB	Time stamp
1	59	UBM and electroless adj plating and solder adj bump and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 13:17
2	46	UBM and electroless adj plating and solder adj bump and nickel and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 13:37
3	9	UBM and electroless adj plating and solder adj bump and nickel and Zinc and 257/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 13:37